

3EC-M1S-HTE

- ・ 于回火后之高伸率及高耐曲折特性, 等同于压延铜箔(RA)。
High Elongation and flexibility after annealing, equally with RA copper foil.
- ・ 于S面微细的表面处理技术、让3EC-M3S-HTE具更低的处理面粗糙度。
Lower profile compare with 3EC-M3S-HTE because of S-side surface treatment.

用途/Application

- ・ 软性电路板
/Flexible Print Board

构成/Composition



生产地点/Production Site

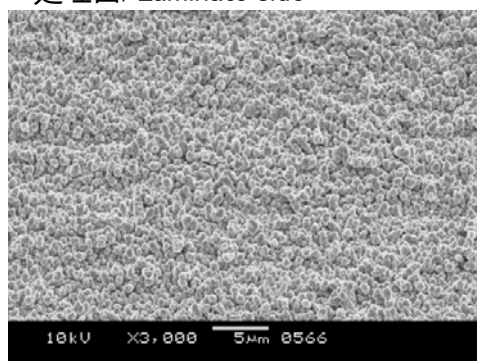
- ・ 日本/Japan

代表性特性数据/Representative data

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ^{@FR-4}
3EC-M1S-HTE	9	78	1.8	390	5	0.6
	12	99	1.8	390	6	0.7

※上述表列为代表性数据非保证值
This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/ resist side

